

ABSTRACT OF DISCLOSURE

A process for fabricating a leadless plastic chip carrier includes laminating a first metal strip to a second metal strip to form a leadframe strip, selectively etching the first metal strip to define at least a row of contact pads, mounting a semiconductor die to either a die attach pad or the second metal strip and wire bonding the semiconductor die to ones of the contact pads, encapsulating a top surface of the leadframe strip in a molding material, removing the second metal strip, thereby exposing the die attach pad and the at least one row of contact pads, and singulating the leadless plastic chip carrier from the leadframe strip.